

CIRCUIT BOARD WITH EMBEDDED COMPONENTS
AND METHOD OF MANUFACTURE

ABSTRACT

A substrate assembly (10) and method of making same has at least one embedded component (25) in a via (24) of a substrate core (22) and includes a first adhesive layer (20) coupled to the substrate core, and a second adhesive layer (26) on at least portions of a top surface of the substrate core and above portions of the embedded component. The substrate assembly can further include a first conductive layer (18) adhered to the bottom surface of the substrate core and a second conductive layer (28) on the second adhesive layer. The substrate assembly can further include an interconnection (36) between a conductive surface of the embedded component and at least one among the first conductive layer and the second conductive layer. The interconnection can be formed through an opening (34) that at least temporarily exposes at least a conductive surface (32) of the embedded component.